Power MOSFET

-20 V, -1.37 A, Single P-Channel, SC-70

Features

- Leading -20 V Trench for Low R_{DS(on)}
- -2.5 V Rated for Low Voltage Gate Drive
- SC-70 Surface Mount for Small Footprint (2x2 mm)
- Pb-Free Package is Available

Applications

- High Side Load Switch
- Charging Circuit
- Single Cell Battery Applications such as: Cell Phones, Digital Cameras, PDAs

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parame	Symbol	Value	Units		
Drain-to-Source Voltage			V_{DSS}	-20	V
Gate-to-Source Voltage			V _{GS}	±8	V
Continuous Drain	Steady	T _A = 25°C	I _D	-1.37	Α
Current (Note 1)	State	T _A = 70°C		-0.62	
Power Dissipation (Note 1)	Steady State	T _A = 25°C	P _D	0.329	W
Pulsed Drain Current t _p = 10 μs			I _{DM}	-4.0	Α
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 150	°C
Source Current (Body Diode), Continuous			Is	-0.5	Α
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Units
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	380	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1

1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).

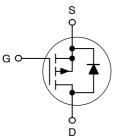


ON Semiconductor®

http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max
	83 m Ω @ –4.5 V	
-20 V	88 mΩ @ –3.6 V	–1.37 A
	104 mΩ @ -2.5 V	

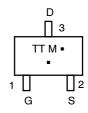
P-Channel MOSFET



MARKING DIAGRAM & PIN ASSIGNMENT



SC-70/SOT-323 CASE 419 STYLE 8



TT = Device Code

M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NTS4101PT1	SOT-323	3000/Tape & Reel
NTS4101PT1G	SOT-323 (Pb-Free)	3000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_{.I}=25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-20	-24.5		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				-13.7		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = -16 V	T _J = 25°C			-1.0	μΑ
		V _{DS} = −16 V	T _J = 70°C			-5.0	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _G	_{iS} = ±8 V			±100	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= -250 μΑ	-0.45	-0.64	-1.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				2.7		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = -4.5 V, I	_D = -1.0 A		83	120	mΩ
		V _{GS} = -3.6 V, I	_D = -0.7 A		88	130	
		$V_{GS} = -2.5 \text{ V}, I_D = -0.3 \text{ A}$			104	160	
Forward Transconductance	G _{FS}	$V_{DS} = -5.0 \text{ V}, I_D = -1.3 \text{ A}$			5.2		S
CHARGES AND CAPACITANCES	•		•		•		•
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = -20 \text{ V}$			603	840	pF
Output Capacitance	C _{OSS}				90	125	
Reverse Transfer Capacitance	C _{RSS}				62	85	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -4.5 \text{ V}, V_{E}$ $I_{D} = -1.0$	_{OS} = -4.5 V,		6.4	9.0	nC
Threshold Gate Charge	Q _{G(TH)}	I _D = -1.0 A			0.7		
Gate-to-Source Charge	Q_{GS}				1.0		1
Gate-to-Drain Charge	Q_{GD}				1.5		
SWITCHING CHARACTERISTICS (No	ote 3)		•		•		•
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = -4.5 \text{ V}, V_{D}$	_{DD} = -4.0 V,		6.2	12	ns
Rise Time	t _r	$I_D = -1.0 \text{ A}, R_G = 6.2 \Omega$			14.9	25	
Turn-Off Delay Time	t _{d(OFF)}				26	40	
Fall Time	t _f				18	30	
DRAIN-SOURCE DIODE CHARACTE	RISTICS		•		•		•
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 V$	T _J = 25°C		-0.61	-1.2	V
		$I_S = -0.3 \text{ A}$	T _J = 125°C		-0.5		
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dI_{SD}/dt = 100 A/ μ s, I_{S} = -1.0 A			10.9	20	ns
Charge Time	T _a				7.1		
Discharge Time	T _b				3.8		
Reverse Recovery Charge	Q _{RR}				4.25		nC

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

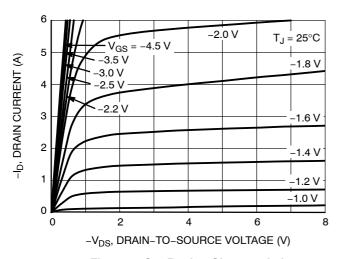


Figure 1. On-Region Characteristics

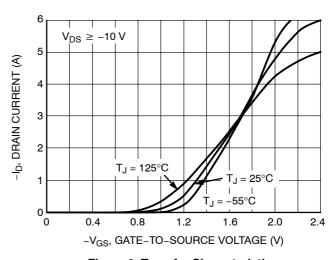


Figure 2. Transfer Characteristics

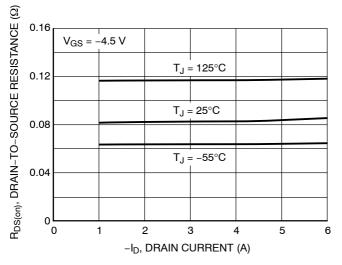


Figure 3. On–Resistance versus Drain Current and Temperature

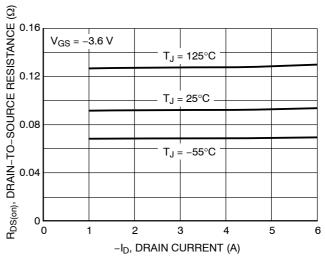


Figure 4. On-Resistance versus Drain Current and Temperature

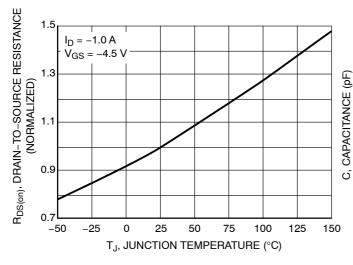


Figure 5. On–Resistance Variation with Temperature

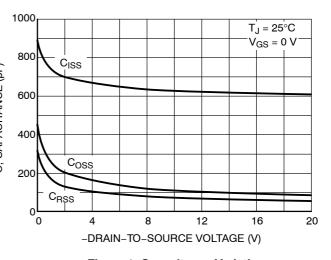


Figure 6. Capacitance Variation

TYPICAL CHARACTERISTICS

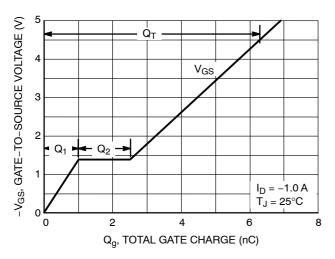


Figure 7. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

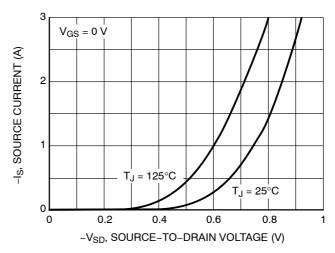
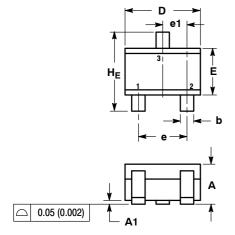


Figure 8. Diode Forward Voltage versus Current

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE N





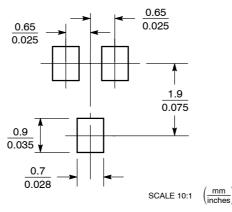
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.032	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2	0.70 REF			0.028 REF			
b	0.30	0.35	0.40	0.012	0.014	0.016	
С	0.10	0.18	0.25	0.004	0.007	0.010	
D	1.80	2.10	2.20	0.071	0.083	0.087	
E	1.15	1.24	1.35	0.045	0.049	0.053	
е	1.20	1.30	1.40	0.047	0.051	0.055	
e1	0.65 BSC			0.026 BSC			
L	0.20	0.38	0.56	0.008	0.015	0.022	
HE	2.00	2.10	2.40	0.079	0.083	0.095	

STYLE 8: PIN 1. GATE 2. SOURCE 3. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5773–3850 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative